

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: H. KOMATSU, et al.
Serial No.: 10/594,548
Filed: SEPTEMBER 27, 2006
For: HEAT-RESISTANT PHOTOSENSITIVE RESIN
COMPOSITION, METHOD FOR FORMING PATTERN USING
THE COMPOSITION, AND ELECTRONIC PART
Group AU: 1795
Examiner: John S. Y. Chu
Confirm. No.: 3540

RESPONSE**Mail Stop: AMD – NO FEE**

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

June 18, 2010

Sir:

In response to the Office Action mailed May 18, 2010, Applicants respectfully elect the Group I claims (that is, claims 1, 2, 5-9 and 11-18). This election is made with traverse, for reasons as set forth in the following.

Thus, it is noted that claim 1 recites a photosensitive resin composition, while claim 10 recites a method for forming a pattern using such photosensitive resin composition. The method as set forth in claim 10 includes exposing the photosensitive resin film to light and then developing the exposed photosensitive resin film. It is respectfully submitted that claim 10 defines a method following from the photosensitive resin composition of claim 1, and should be considered together with this method.

It is respectfully submitted that as claim 1 recites a photosensitive resin composition, while claim 10 recites a patterning method using such composition, examination of the Group I and Group II claims would not impose a serious burden